PHIXEL WIF - POST DICING WAFER AOI

Minimize waste and loss in the wafer dicing process

The most cost-efficient diced-wafer inspection system on the market. With ultra-high-speed vision scan and high-precision wafer 2D inspection, the Post Dicing Wafer AOI enables conversion for 6", 8", and 12" wafer frame film carrier cassette. It guarantees the quality of diced wafer, allows a fast feedback loop, and prevents wafer yield loss. When cost and quality of manufacturing are a concern, this diced-wafer inspection system offers a tight wafer supply to eliminate wafer damage due to dicing issues. WIF offers inspection after wafer dicing to detect surface defects or inspection after package singulation of DFN to detect package, mark, lead, and plating defects. Advanced Defect Classification (ADC) by hybrid analysis will enhance manufacturing efficiency and competitiveness.

Key features

Application

- Inspection after wafer dicing to detect surface defects
- Inspection after package singulation to detect package, mark, lead, and plating defects

Key features

- 2D surface inspection, stationary camera
- 128-thread processor
- 16K line scan camera resolution
- Supports high-density wafer up to 500K dies
- FOV 25 mm with 2 magnifications selection or 0.85 µm by upscaled image
- Auto 2D barcode reading
- Hi-end vision performance
- High throughput at high-volume manufacturing rate
- Granit base inspection work holder
- Supports 6", 8", 12" wafer Automatic wafer map match
- Two cassettes at input loader
- SEMI standard with SECS/GEM interface

Specifications

Imaging system

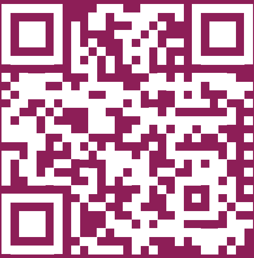
- Camera: 16K line scan monochrome
- Number of cameras: 1
- 1.7 µm or 3.4 µm pixel resolution by pixel binning
- Minimum object detection: 12 µm
- Lighting: Coaxial

Inspection categories

- Program mode: Fast programming for common reject criteria
- Reject treatment: Electronic wafer map
- Inspection view: Top view

Inspection items

- Die related: Chipping. Damaged bump larger than percentage of bump area. Bump diameter. Shorted umps contact. Missing bump. Scratch. Probe mark size larger than percentage of bump area. Cracked die. Kerf shifting. Discoloration



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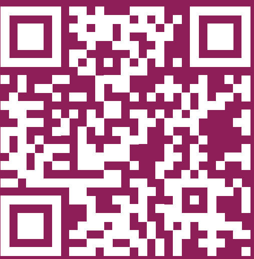

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